



Sheet 1 of 1

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## INFORMATION DISCLOSURE STATEMENT

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APPLICANT(S): Barstad et al.

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May 17, 1999

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## UNITED STATES PATENT DOCUMENTS

EXAM. INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FIL. DATE IF APPR
W.	AA	3,876,513	04/08/75	Brown et al.			
	AB	4,098,656	07/04/78	Deuber			
	AC	4,530,741	07/23/85	Rosenberg			
	AD	4,913,787	04/03/90	Kiso			
	AE	5,051,154	09/24/91	Bernards et al.			
	AF	5,068,013	11/26/91	Bernards et al.			
	AG	5,174,886	12/29/92	King et al.			
	AH	5,223,118	06/29/93	Sonnenberg et al.			
	AJ	5,858,870	01/12/99	Zheng et al.			
	AK	5,433,840	07/95	Dahms et al.			
	AL	2,424,887	07/47	Henricks			
W.	AM	5,151,170	09/92	Montgomery et al.			
	AN	4,347,108	08/82	Willis			
W.	AO	4,336,114	06/82	Mayer et al.			
	AP	4,036,710	07/77	Kardos et al.			
	AQ	6,113,771	09/00	Landau et al.			
	AR	5,068,013	11/91	Bernards et al.			
	AS	5,051,154	09/91	Bernards et al.			
W.	AT	6,024,857	02/00	Reid			

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## OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

W.	BA	Shipley Advance Interconnect, Advanced Interconnect Materials, "Nanoplate" Copper Plating Electrolyte Optimized for 200 nm, Bottom-up Trench Fill" Shipley Company, L.L.C. data sheet. Date not known.
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Examiner:

W. J. A. R.

Date:

8/27/02